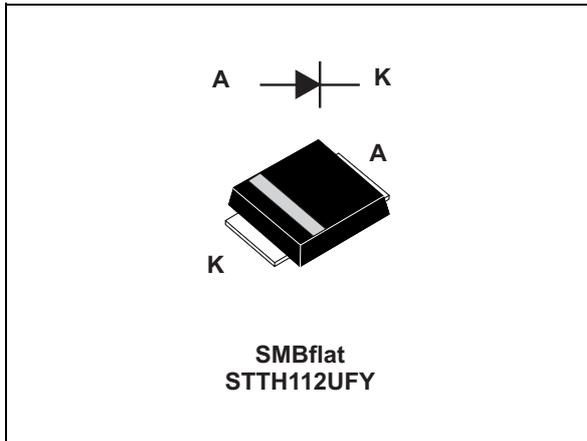


## Automotive high voltage ultrafast rectifier

Datasheet - production data


**Features**

- Very low conduction losses
- Negligible switching losses
- Low forward and reverse recovery times
- High junction temperature
- AEC-Q101 qualified
- ECOPACK<sup>®</sup>2 compliant component

**Description**

The STTH112-Y, which is using ST's new 1200 V planar technology, is especially suited for switching mode base drive and transistor circuits.

The device is also intended for use as a free wheeling diode in power supplies and other power switching applications in automotive functions.

**Table 1. Device summary**

Symbol	Value
$I_{F(AV)}$	1 A
$V_{RRM}$	1200 V
$T_{j(max)}$	175 °C
$V_F (typ)$	1.1 V
$T_{rr} (typ)$	53 ns

# 1 Characteristics

**Table 2. Absolute ratings (limiting values at  $T_j = 25\text{ °C}$ , unless otherwise specified)**

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	1200	V
$I_{F(AV)}$	Average forward current	$T_L = 135\text{ °C}, \delta = 0.5$	A
$I_{FSM}$	Forward Surge current	$t_p = 8.3\text{ ms}$	A
$T_{stg}$	Storage temperature range	-65 to + 175	°C
$T_j^{(1)}$	Operating temperature range	-40 to + 175	°C

1.  $\frac{dP_{Tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter	Value	Unit
$R_{th(j-l)}$	Junction to lead	20	°C/W

**Table 4. Static electrical characteristics**

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$		5	$\mu\text{A}$
		$T_j = 125\text{ °C}$		1	50	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 1\text{ A}$		1.9	V
		$T_j = 150\text{ °C}$		1.10	1.55	

1. Pulse test:  $t_p = 5\text{ ms}, \delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}, \delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 1.25 \times I_{F(AV)} + 0.30 I_{F(RMS)}^2$$

**Table 5. Dynamic electrical characteristics**

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$T_j = 25\text{ °C}$ $I_F = 0.5\text{ A}, I_{rr} = 0.25\text{ A}$ $I_R = 1\text{ A}$		53	75	ns
$t_{fr}$	Forward recovery time	$T_j = 25\text{ °C}$ $I_F = 1\text{ A}, dI_F/dt = 50\text{ A}/\mu\text{s}$ $V_{FR} = 4.5\text{ V}$			500	
$V_{FP}$	Forward recovery voltage			20	30	V

Figure 1. Average forward power dissipation versus average forward current

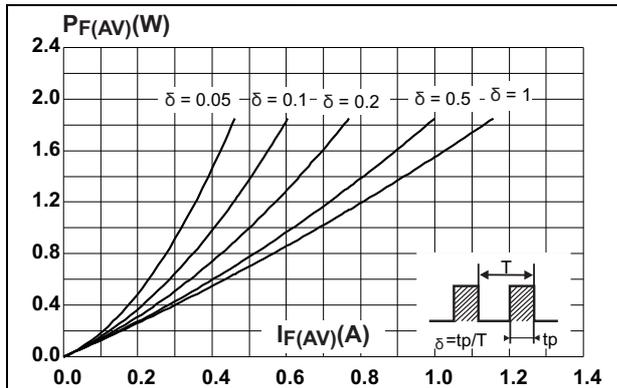


Figure 2. Forward voltage drop versus forward current (typical values)

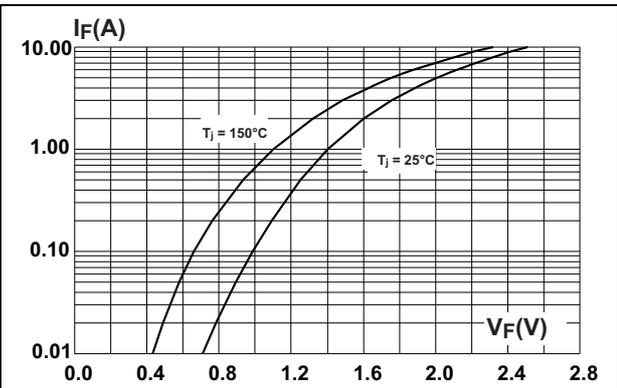


Figure 3. Forward voltage drop versus forward current (maximum values)

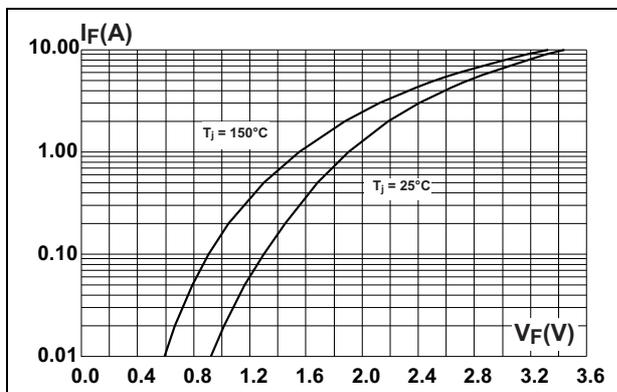


Figure 4. Relative variation of thermal impedance junction to lead versus pulse duration

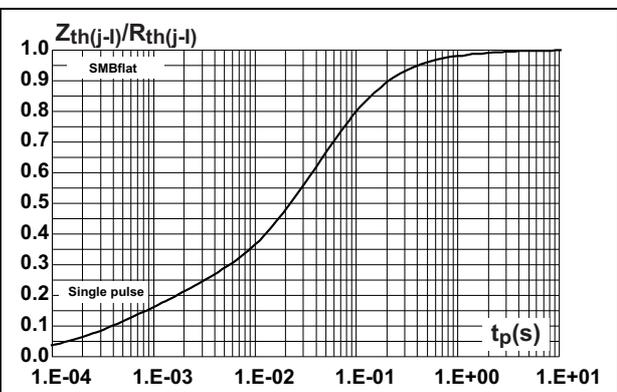


Figure 5. Junction capacitance versus reverse voltage applied (typical values)

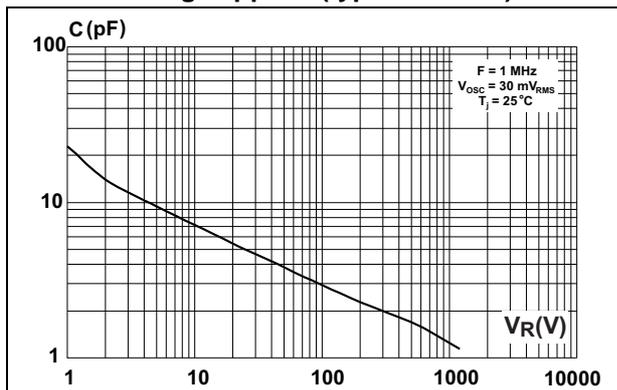
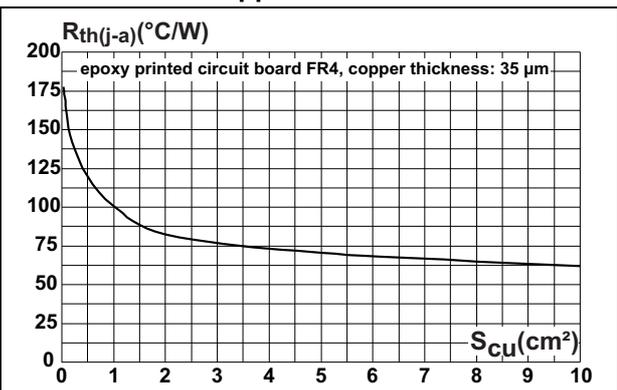


Figure 6. Thermal resistance junction to ambient versus copper surface under each lead



## 2 Package information

- Epoxy meets UL94,V0
- Lead-free package
- Band indicates cathode

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

Figure 7. SMBflat dimensions definitions

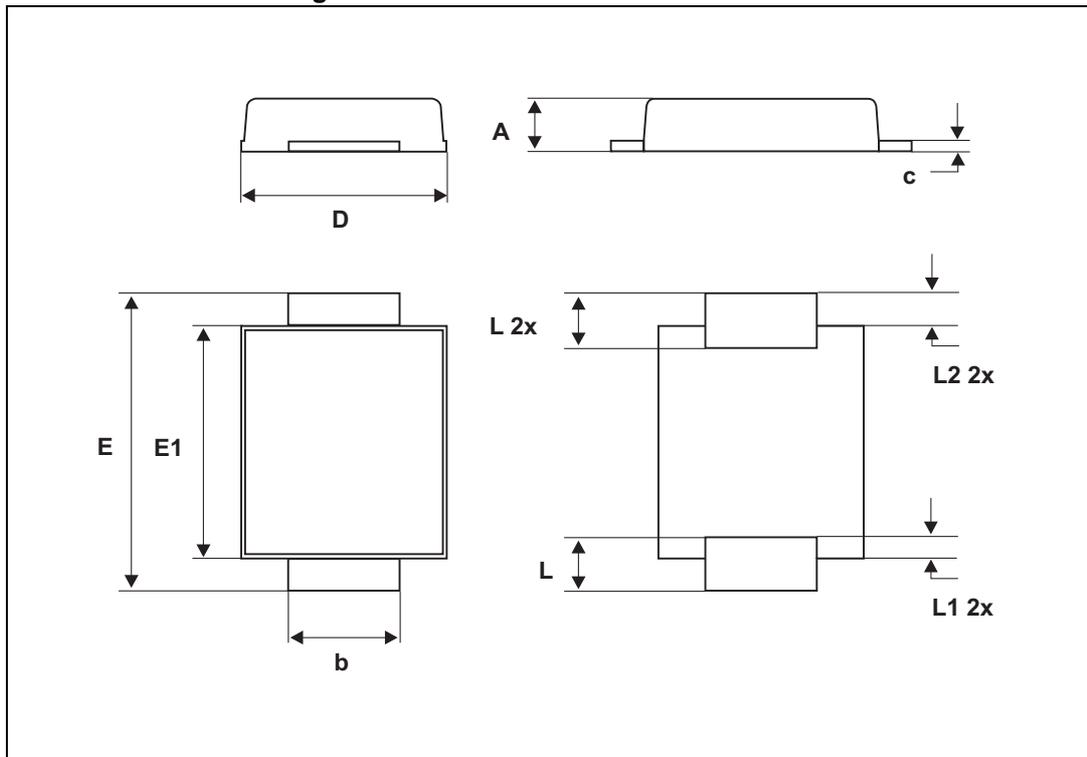
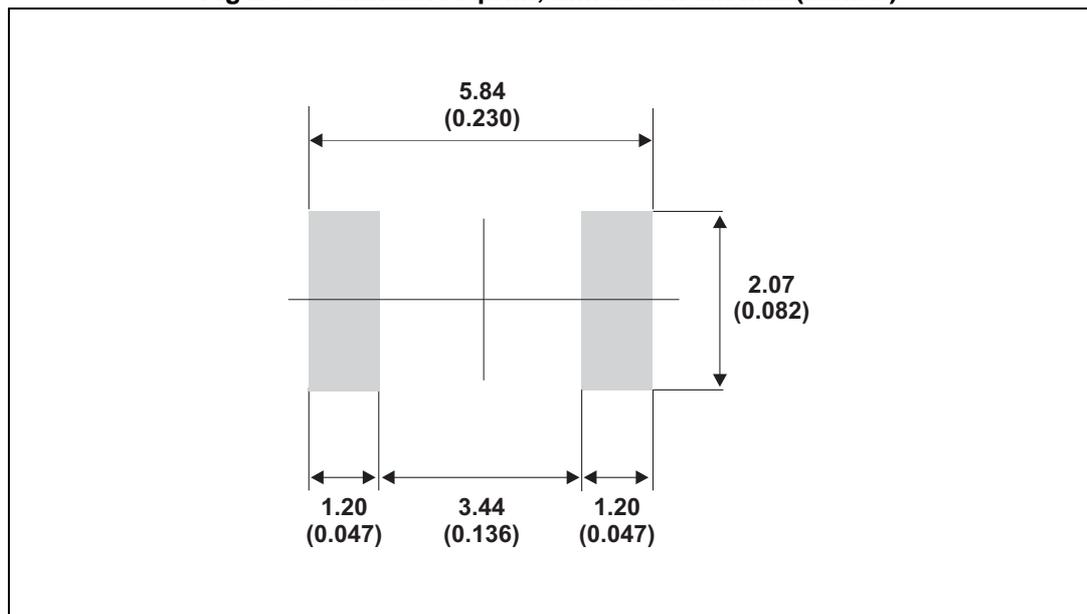


Table 6. SMBflat dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.10	0.035		0.043
b	1.95		2.20	0.077		0.087
c	0.15		0.40	0.006		0.016
D	3.30		3.95	1.30		0.156
E	5.10		5.60	0.200		0.220
E1	4.05		4.60	0.189		0.181
L	0.75		1.50	0.029		0.059
L1		0.40			0.016	
L2		0.60			0.024	

Figure 8. SMBflat footprint, dimensions in mm (inches)



### 3 Ordering information

Table 7. Ordering information

Order codes	Marking	Package	Weight	Base qty	Delivery mode
STTH112UFY	F112Y	SMBflat	50 mg	5000	Tape and reel

### 4 Revision history

Table 8. Document revision history

Date	Revision	Changes
04-Feb-2014	1	Initial release.

**Please Read Carefully:**

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

**UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.**

**ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.**

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.  
Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2014 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

[www.st.com](http://www.st.com)

